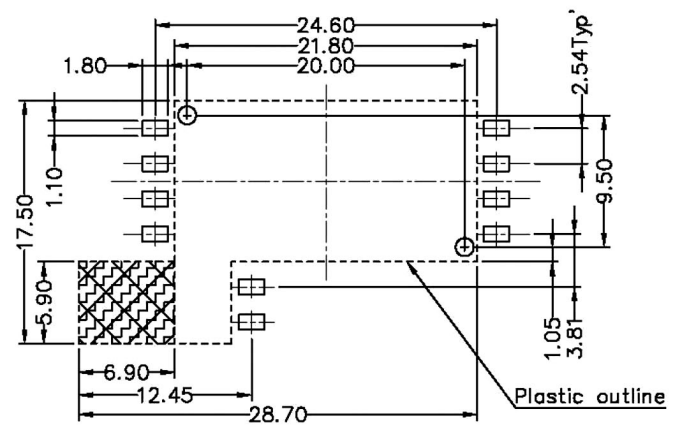
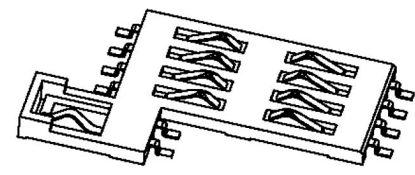


- Specification**
- General Information**
    - Contact Principle: Friction Technology
    - Mounting Type: SMT
    - Switch: Blade Contact, Normal Open
    - Data Contact Material: Copper Alloy
    - Insulator Material: Thermoplastic UL94V-0
    - Data Contacts Plating: Gold Flash Over Nickel
  - Electrical Specification**
    - Contact Resistance: 50m ohms Max
    - Insulator Resistance: 1000M ohms Min
    - Dielectrical Withstanding Voltage: 500V AC
    - Voltage Rating: 30V AC R.M.S. 1 Min (Sea Level)
    - Current Rating: 1A Max, 10uA Min
  - Mechanical Specification**
    - Contact Force: 0.2N~0.6N
    - Durability: 100,000 Cycles Min
  - Environmental Specification**
    - Operating Temperature: -20°C~+70°C
    - Operating Humidity: 20%~95% RH
    - Solderability: 1) Vapor Phase : 215°C, 30 Sec Max.
    - 2) IR Re-Flow : 230°C, 15 Sec Max.
    - 3) Manual Soldering: 360°C, 3 Sec Max.
    - RoHS compliant



**Reference PCB Layout**  
(.xx±0.05)

<b>RoHS Compliant</b>		<b>HSM 玄茂科技股份有限公司</b> <b>HSUAN MAO TECHNOLOGY CO., LTD.</b>	
APPD. 核准 <b>Angel</b>		UNLESS OTHERWISE SPECIFIED TOLERANCES ARE .X ±0.38 .XX ±0.25 ANG. ±1°	<b>PART NAME 品名</b> SIM CARD BLOCK W/LEFT SWITCH 8P SMT ROW SPACING:24.6mm HEIGHT:1.4mm SELECTIVE GOLD BLACK ROHS
DWG. 製圖 <b>Yumi</b>	SCALE 比例 參考 UNIT 單位 M M PAGE 張數 1 OF 1	SIZE 紙張尺寸 A 4 REV. 版次 A	<b>PART NO. 料號</b> <b>C0614-08DLDSB0R</b>
DATE 制表日 <b>2009/07/02</b>			